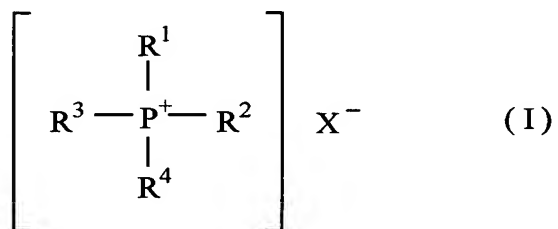
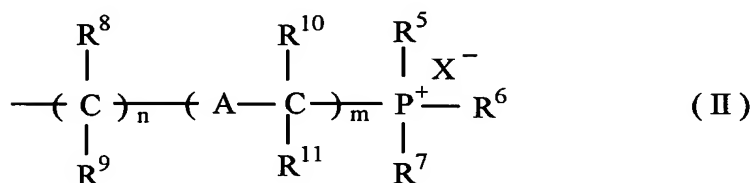


CLAIMS

1. An epoxy resin composition comprising an epoxy resin, a hardening agent and a hardening accelerator as indispensable ingredients, wherein said hardening accelerator is a phosphonium compound represented by the following formula (I):



- wherein R^1 to R^4 are the same or different, and are an optionally substituted alkyl group, an optionally substituted aryl group, an optionally substituted aralkyl group, an optionally substituted diarylmethyl group or a group represented by the following formula (II):



- wherein R^5 to R^7 are the same or different, and are an optionally substituted alkyl group, an optionally substituted aryl group, an optionally substituted aralkyl group or an optionally substituted diarylmethyl group, R^8 to R^{11} are the same or different, and are a hydrogen atom,

an optionally substituted alkyl group or an optionally substituted aryl group,

A is an optionally substituted aromatic hydrocarbon ring,

n is an integer of 1 to 5, m is 0 or 1, and

5 X represents a halogen atom, and SbF_6 , AsF_6 , PF_6 , BF_4 or BPh_4 ;

provided that at least one of R^1 to R^4 is a group represented by the formula (II),

10 or any one of R^1 to R^4 and any one of R^5 - R^7 may be combined together to form a lower alkylene group which forms a heterocyclic ring containing two phosphorus atoms, and X is as defined in the formula (II).

2. The epoxy resin composition according to claim 1 wherein the phosphonium compound is one or more kinds of
15 phosphonium compound selected from the group consisting of (a) a phosphonium compound wherein, in the above formula (I), at least one of R^1 to R^4 is a group represented by the formula (II), R^5 to R^7 are the same or different, and are a phenyl group, an optionally substituted benzyl group, a
20 naphthylmethyl group, an optionally substituted diphenylmethyl group or an optionally substituted alkyl group, R^8 is a hydrogen atom, R^9 is a hydrogen atom or a phenyl group, n is an integer of 1 to 4, m is 0, and the rest of R^1 to R^4 is a phenyl group, an optionally
25 substituted benzyl group, a naphthylmethyl group, an

optionally substituted diphenylmethyl group or an optionally substituted alkyl group,

(b) a phosphonium compound wherein, in the above formula (I), R^2 is a group represented by the formula (II), R^6 , R^7 and R^9 are a phenyl group, R^8 is a hydrogen atom, m is 0, n is 2, R^1 and R^5 are combined together to form a C_{1-4} alkylene group, and R^3 and R^4 are a phenyl group,

(c) a phosphonium compound wherein, in the above formula (I), R^1 is a group represented by the formula (II), R^5 to R^7 are a phenyl group or a group represented by the formula: $-(CH_2)_p-PPh_2$ (wherein, p is an integer of 1 to 4), R^8 to R^{11} are a hydrogen atom, A is an optionally substituted benzene ring, m and n are 1, and R^2 to R^4 are a phenyl group or a group represented by the formula: $-(CH_2)_p-PPh_2$ (wherein, p is an integer of 1 to 4),

(d) a phosphonium compound wherein, in the above formula (I), R^2 is a group represented by the formula (II), R^6 and R^7 are a phenyl group, R^8 to R^{11} are a hydrogen atom, A is an optionally substituted benzene ring, m and n are 1, R^1 and R^5 are combined together to form a C_{1-8} alkylene group, and R^3 and R^4 are a phenyl group.

3. The epoxy resin composition according to claim 1, wherein the amount of a phosphonium compound to be added is 0.05 to 5 parts by weight (phr) relative to 100 parts by weight (phr) of epoxy resin.

4. The epoxy resin composition according to claim 1, wherein the epoxy resin comprises a triazine derivative epoxy resin.

5. A hardened resin which is obtained by heating
5 and curing the epoxy resin composition according to claim 1.